



Recommended soldering conditions

The lead-free termination MLCCs are not only to be used on SMT against lead-free solder paste, but also suitable against lead-containing solder paste. If the optimized solder joint is requested, increasing soldering time, temperature and concentration of N₂ within oven are recommended.

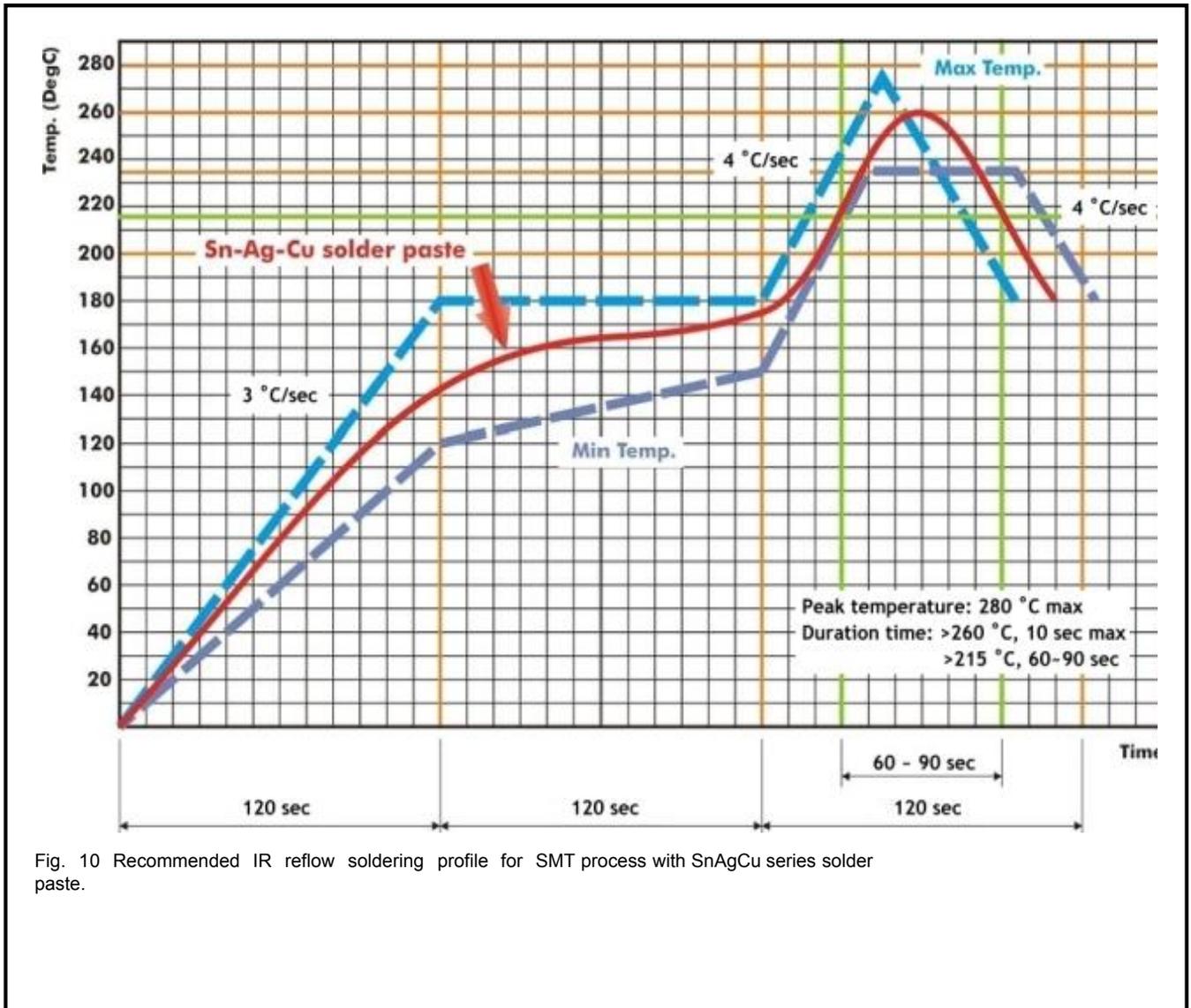


Fig. 10 Recommended IR reflow soldering profile for SMT process with SnAgCu series solder paste.